



SN 09/945,397

PATENT#9B  
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2-10-03IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Gurtej Singh Sandhu et al.  
Examiner: Judith A. Cothorn  
Serial No.: 09/945,397  
Group Art Unit: 2822  
Filed: August 30, 2001  
Docket: 303.541US2  
Title: CONDUCTIVE CONTAINER STRUCTURES HAVING A DIELECTRIC CAP

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents  
Washington, D.C. 20231

In response to the Office Action mailed on October 7, 2002. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a one-month extension of the period for responding to the Office action, thereby moving the deadline for response from January 7, 2003 to February 7, 2003.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect addition of new claims 117-121.

117. (New) A method of forming a semiconductor structure, comprising the following processing steps in the order presented:  
forming an insulating layer on a substrate;  
forming an opening in the insulating layer, wherein the opening has a bottom on an exposed portion of the substrate and sidewalls defined by the insulating layer;  
forming a conductive layer on the insulating layer and the exposed portion of the substrate;  
forming a fill layer on the conductive layer, wherein the fill layer fills the opening;  
removing the conductive layer and the fill layer to a level below a top of the insulating layer, thereby forming a container structure having sidewalls comprised of the conductive layer on the sidewalls of the opening, and a closed bottom comprised of the conductive layer on the bottom of the opening;

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